

L31	81	(wafer substrate) and stage same (wafer adj3 (holder cassette convey\$3) collet) and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 20:22
L32	184	(wafer substrate) and stage and (wafer adj3 (holder cassette convey\$3) collet) and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 20:31
L33	11507	(intermediate preparatory) with stage and (wafer substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 20:32
L34	6644	(intermediate preparatory) adj3 stage and (wafer substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 20:33
L35	849	(intermediate preparatory) adj3 stage and (wafer substrate) and (holder cassette collet convey)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 20:34
L36	14	(intermediate preparatory) adj3 stage and (wafer substrate) and (holder cassette collet convey) and (first lower) adj2 (chip die ic) and (second upper) adj2 (chip die ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 20:36
L37	505	stage and (wafer substrate) and (holder cassette collet convey) and (first lower) adj2 (chip die ic) and (second upper) adj2 (chip die ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 20:36
L38	3	("4166563" "4245768" "4247034").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/06 20:54

L21	0	uebayashi-t-\$.in. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 19:55
L22	0	uebayashi-t-\$.IN. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 19:55
L23	33	ball-m-\$.IN. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 19:56
L24	0	yamazaki-a-\$.IN. and die adj bonding	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 19:57
L25	0	jp-10032307-\$.ccls.	JPO	OR	OFF	2005/08/06 20:11
L26	276464	(wafer substrate) and stage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 20:12
L27	7112	(wafer substrate) and stage and (wafer adj3 (holder cassette convey\$3) collet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 20:15
L28	3257	(wafer substrate) same stage same (wafer adj3 (holder cassette convey\$3) collet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 20:16
L29	56	(wafer substrate) same stage same (wafer adj3 (holder cassette convey\$3) collet) and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 20:22
L30	16	("3811182" "4185814" "4634043" "4875279" "5049084" "5169196" "5639323" "5654204" "5765277" "5839769" "5877534" "5943254" "5983477" "6068317" "6152506" "6196439").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/06 20:18

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L9	4497	shibaura.as.	JPO	OR	OFF	2005/08/06 19:47
L10	386	shunichi.as.	JPO	OR	OFF	2005/08/06 19:48
L11	2	shunichi.as. and wafer	JPO	OR	OFF	2005/08/06 19:48
L12	5	shunichi.as. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/06 19:49
L13	1000	renesas.as. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/06 19:49
L14	459	renesas.as. and wafer and (chip die ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/06 19:50
L15	235	renesas.as. and wafer and (chip die ic) and stage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 19:50
L16	3	renesas.as. and wafer and (chip die ic) and stage and wafer adj holder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 19:51
L17	0	abe-s-\$.in. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 19:52
L18	0	abe-shunichi-\$.in. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 19:53
L19	0	uebayashi-t-\$.in. and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 19:54
L20	406630	"uebayashi-t-\$.in.and" wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/06 19:55